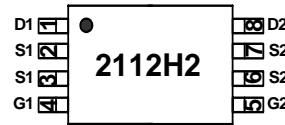
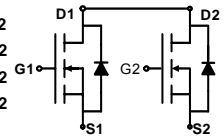


**Main Product Characteristics:**

$V_{DSS}$	20V
$R_{DS(on)}$	10mohm(typ.)
$I_D$	8A


**TSSOP-8**

**Marking and pin Assignment**

**Schematic diagram**
**Features and Benefits:**

- Advanced trench MOSFET process technology
- Special designed for battery protection, load switching and general power management
- Ultra low on-resistance with low gate charge
- Fast switching and reverse body recovery
- 150°C operating temperature


**Description:**

It utilizes the latest trench processing techniques to achieve the high cell density and reduces the on-resistance with high repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in battery protection, power switching application and a wide variety of other applications

**Absolute max Rating:**

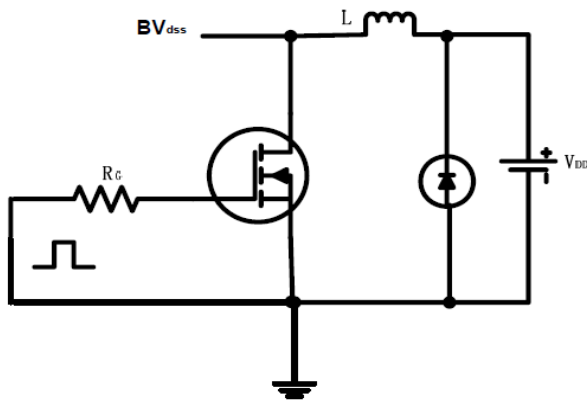
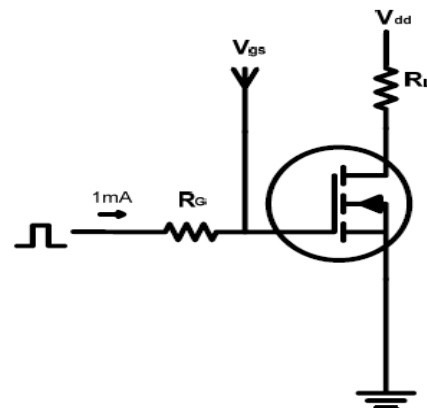
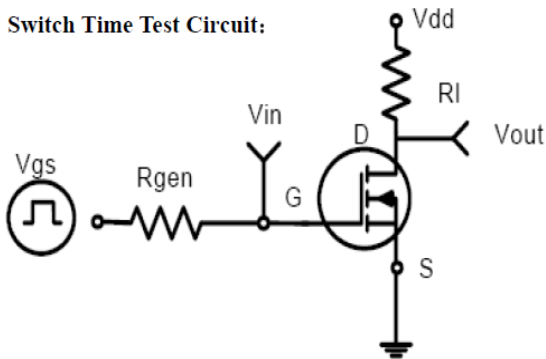
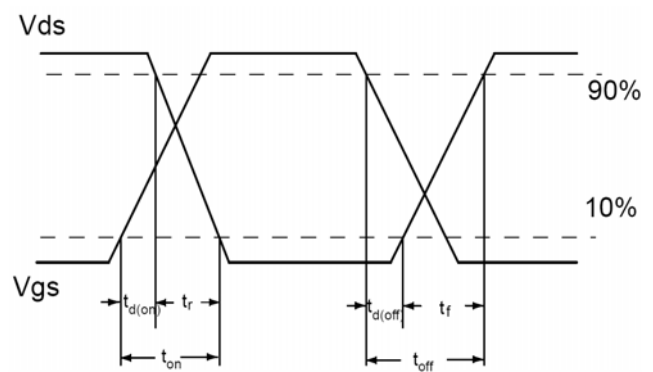
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	±10	V
Drain Current-Continuous@ Current-Pulsed (Note 1)	$I_D$	8	A
	$I_{DM}$	50	A
Maximum Power Dissipation	$P_D$	1.25	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

**Thermal Resistance**

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	100	°C/W
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**Electrical Characterizes @ $T_A=25^{\circ}\text{C}$  unless otherwise specified**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=20V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 10V, V_{DS}=0V$			$\pm 100$	nA
<b>ON CHARACTERISTICS (Note 3)</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	0.7	1.2	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=4.5A$		10	12.5	m $\Omega$
		$V_{GS}=2.5V, I_D=3.5A$		13.2	18.5	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=5V, I_D=4A$	4			S
<b>DYNAMIC CHARACTERISTICS (Note4)</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=8V, V_{GS}=0V,$ $F=800KHz$		1520		PF
Output Capacitance	$C_{OSS}$			229		PF
Reverse Transfer Capacitance	$C_{RSS}$			198		PF
<b>SWITCHING CHARACTERISTICS (Note 4)</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=10V, I_D=1A$ $V_{GS}=4V, R_{GEN}=10\Omega$		18.3		nS
Turn-on Rise Time	$t_r$			4.8		nS
Turn-Off Delay Time	$t_{d(off)}$			43.5		nS
Turn-Off Fall Time	$t_f$			20		nS
Total Gate Charge	$Q_g$	$V_{DS}=10V, I_D=4A,$ $V_{GS}=4V$		19		nC
Gate-Source Charge	$Q_{gs}$			4.2		nC
Gate-Drain Charge	$Q_{gd}$			4.9		nC
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
Diode Forward Voltage (Note 3)	$V_{SD}$	$V_{GS}=0V, I_S=2A$		0.67	1.2	V
Diode Forward Current (Note 2)	$I_S$				8	A

**Test circuits and Waveforms**
**EAS test circuits:**

**Gate charge test circuit:**

**Switch Time Test Circuit:**

**Switch Waveforms:**

**NOTES:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production testing.

Typical electrical and thermal characteristics

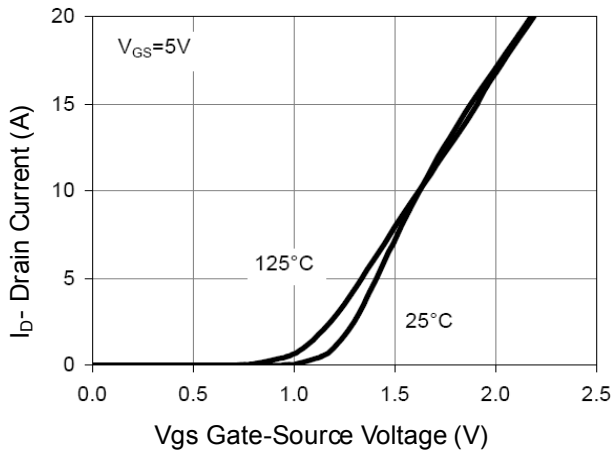


Figure 1: Transfer Characteristics

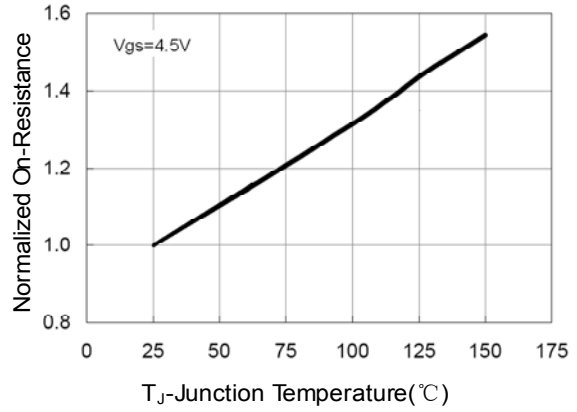


Figure 2: Drain-Source On-Resistance

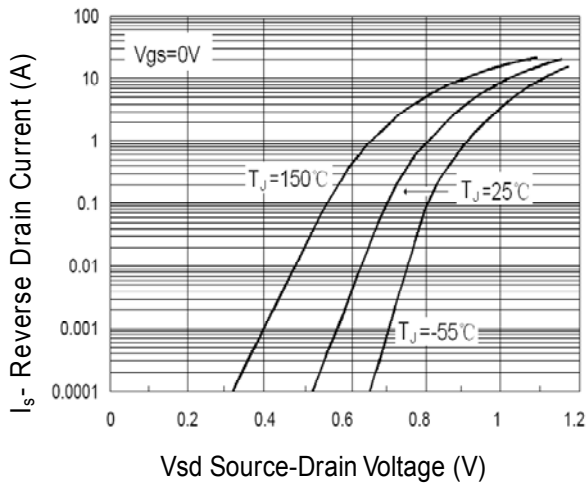


Figure 3 : Source- Drain Diode Forward

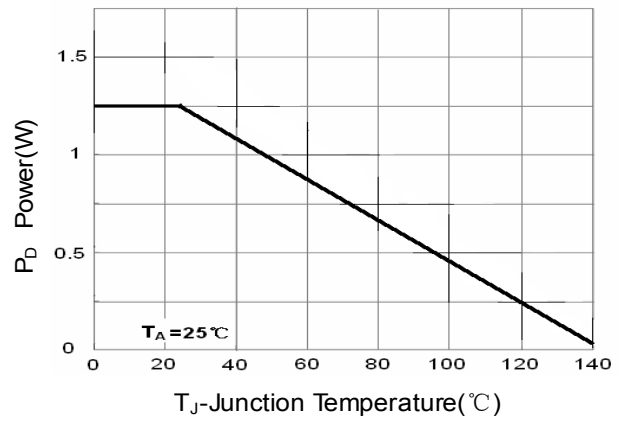


Figure 4: Power Dissipation

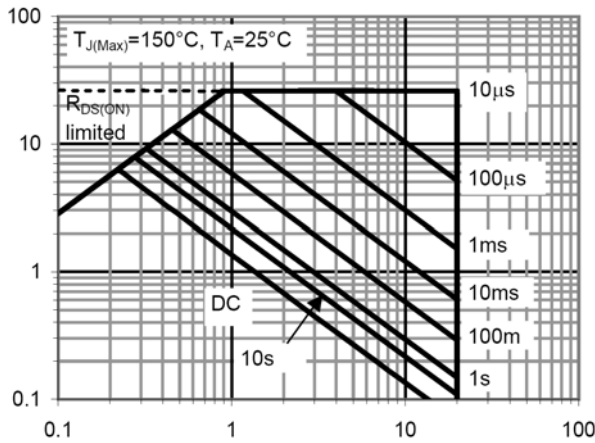


Figure 5: Safe Operation Area

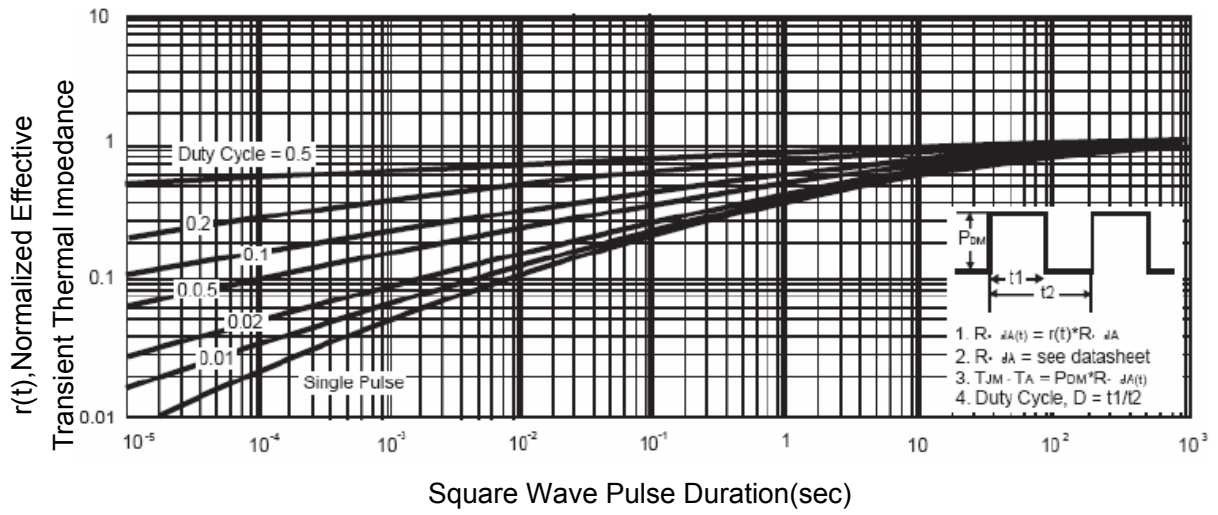
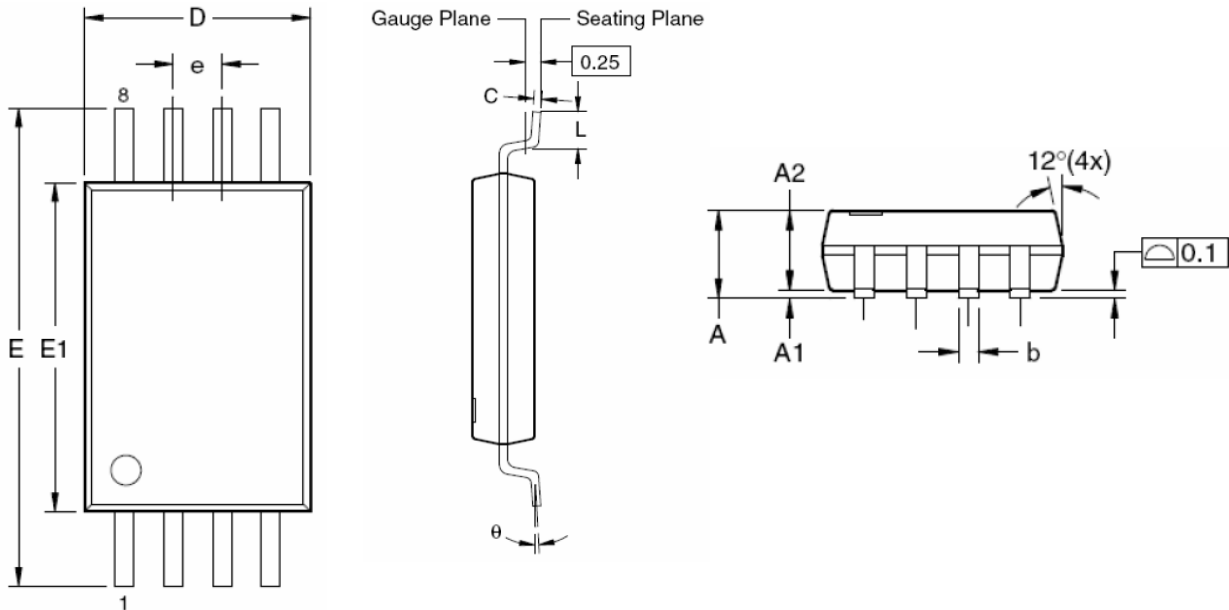
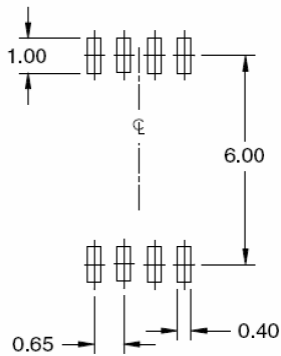


Figure 6: Normalized Maximum Transient Thermal Impedance

**Mechanical Data:**
**TSSOP-8 Dimensions in Millimeters (UNIT:mm)**

**RECOMMENDED LAND PATTERN**


UNIT: mm

**Dimensions in millimeters**

Symbols	Min.	Nom.	Max.
A	—	—	1.20
A1	0.05	—	0.15
A2	0.80	1.00	1.05
b	0.19	—	0.30
C	0.09	—	0.20
D	2.90	3.00	3.10
E	6.40 BSC		
E1	4.30	4.40	4.50
e	0.65 BSC		
L	0.45	0.60	0.75
$\theta$	0°	—	8°

**Dimensions in inches**

Symbols	Min.	Nom.	Max.
A	—	—	0.047
A1	0.002	—	0.006
A2	0.031	0.039	0.041
b	0.007	—	0.012
C	0.004	—	0.008
D	0.114	0.118	0.122
E	0.252 BSC		
E1	0.169	0.173	0.177
e	0.026 BSC		
L	0.018	0.024	0.030
$\theta$	0°	—	8°

**NOTES:**

1. All dimensions are in millimeters.
2. Dimensions are inclusive of plating
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 6 mils.
4. Dimension L is measured in gauge plane.
5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

**Ordering and Marking Information**
**Device Marking: 2112H2**

**Package (Available)**  
**TSSOP-8**  
**Operating Temperature Range**  
**C : -55 to 150 °C**

**Devices per Unit**

Package Type	Units/ Tube	Tubes/ Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TSSOP-8	3000pcs	2pcs	6000pcs	8pcs	48000pcs

**Reliability Test Program**

Test Item	Conditions	Duration	Sample Size
High Temperature Reverse Bias(HTRB)	$T_j=125^{\circ}\text{C}$ or $150^{\circ}\text{C}$ @ 80% of Max $V_{DSS}/V_{CES}/V_R$	168 hours 500 hours 1000 hours	3 lots x 77 devices
High Temperature Gate Bias(HTGB)	$T_j=125^{\circ}\text{C}$ or $150^{\circ}\text{C}$ @ 100% of Max $V_{GSS}$	168 hours 500 hours 1000 hours	3 lots x 77 devices

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